

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:

a. FR4 PER IPC 4101B/24 /26 OR /28

b. SIGNAL LAYERS TO BE 1/2 OZ. COPPER.

c. PLANE LAYERS TO BE 1 OZ. COPPER.

d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR MATTE BLUE, BOTH SIDES.
6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

b. IMMERSION SILVER IAG.
7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%.

b. HOLE DIMENSIONS APPLY AFTER PLATING.

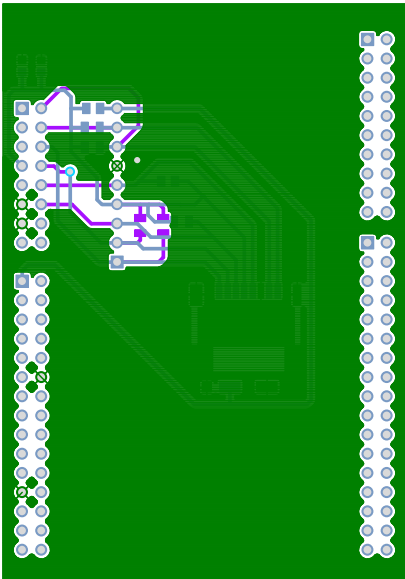
c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003"

e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.



UNLESS OTHERWISE SPECIFIED	DESI
DIMENSIONS ARE IN INCHES	LAYO
TOLERANCES ON:	CHEC
2 PL DECIMALS +/- 0.02"	CID:
3 PL DECIMALS +/- 0.005"	SYST
ANGLES +/- 1 1 Degree	SY
FRACTIONS +	SUBS
	SUI
PROJECT NAME: ProjectName	